

# SYTFL095XG4S

# 9.0 GHz Surface Mount Lowpass Filter

## **Description**

Yantel's surface mount catalog low pass filters utilize Yantel's high dielectric ceramic materials to provide small size and minimal performance variation over temperature. The catalog LPF's are offered with the same footprint in a variety of frequency bands to provide a drop in solution with highly repeatable performance.

#### **Features**

- Small Size
- Fully Shielded Component
- Solder Surface Mount Package
- Moisture Sensitivity Level: MSL1
- Frequency Stable over Temperature
- Operating & Storage Temp: -55°C to +125°C
- Characteristic Impedance: 50Ω

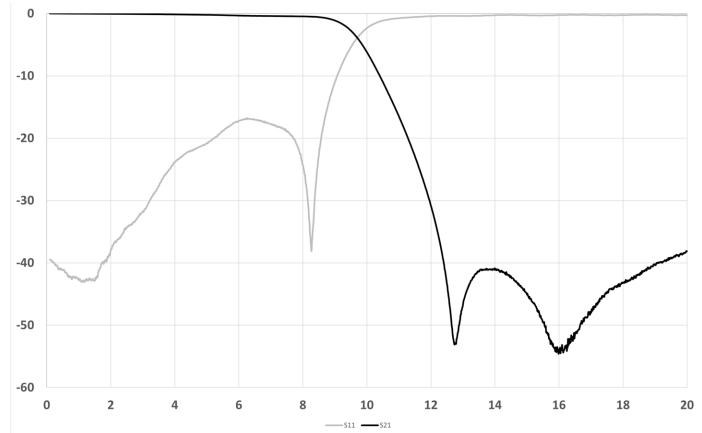
### Specifications\*

Parameter	Frequency Range (GHz)	Min	Тур.	Max
Insertion Loss (dB)	DC - 9.0		1.0	1.5
Return Loss (dB)		10.0	15.0	
High Side Rejection (dB)	11.0 - 20.0	20.0	25.0	
CW Input Power** (W)	DC - 6.0			10
$\theta_{JC} \left( \frac{^{\circ}C}{W} \right)$	7.5			
Size (L x W x H)	5.08 x 4.45 x 2.87 mm			

<sup>\*</sup>Electrical specifications based on typical probed performance at room temperature. Insertion loss shall vary ±0.5dB over temperature.

\*\*Power rating assumes the component will be mounted to a PCB with good thermally conducting

## **Typical Measured Performance**



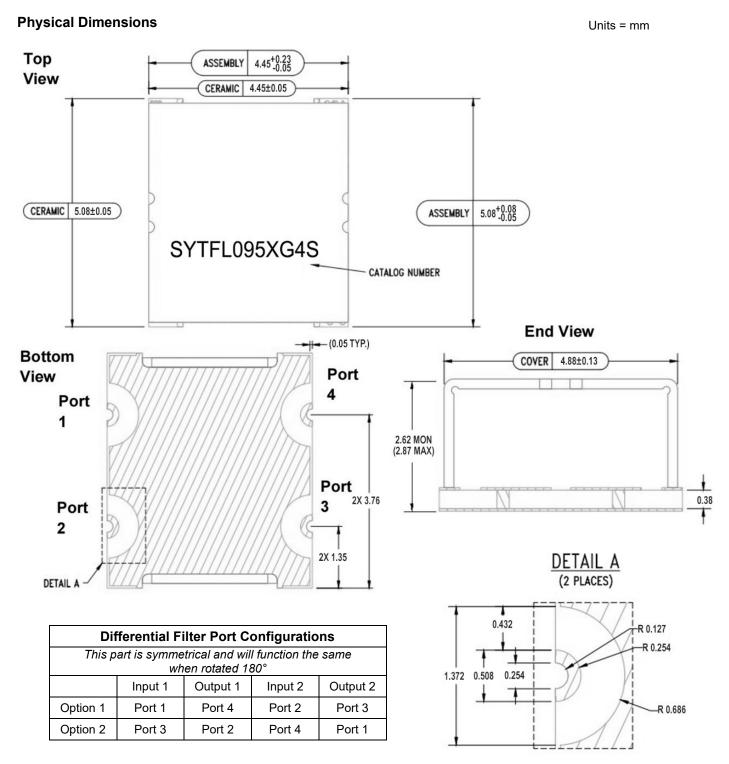
\*Typical de-embedded measured performance mounted on a connectorized test fixture. DEB is 0.254mm RO4350B with 50.00hm CPW ground traces going into the ports at room temperature.

<sup>\*\*</sup>Power rating assumes the component will be mounted to a PCB with good thermally conducting ground vias as outlined in the recommended PCB layout that are connected to an adequate heat sink. Max power is based on 125°C base temperature.



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#### Notes:

1. Termination Finish:

ENIG: 76-152 μm Au over 1270 μm Ni

2. Maximum Assembly Process Temperature: 250°C

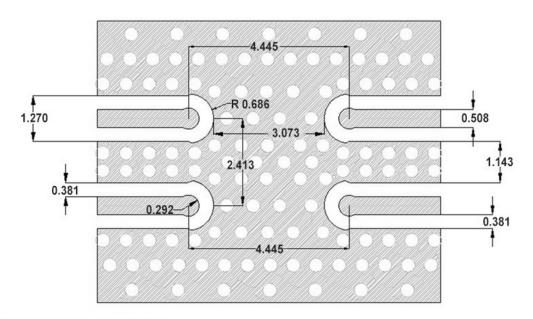


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#### **Recommended PCB Layout**

Unit = mm



### PCB RECOMMENDED STACKUP

Filter is matched to RF layer stackup seen below

Dimensions are specified below in mm (not to scale)

Board material : RO4350b Board material design dk : 3.66

CPWG : 0.51mm trace width, 0.38mm gaps

